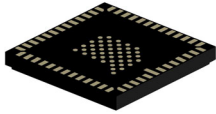


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



mPLCC52 12.00x12.00x1.53, 0.80P
CASE 776AW
ISSUE E

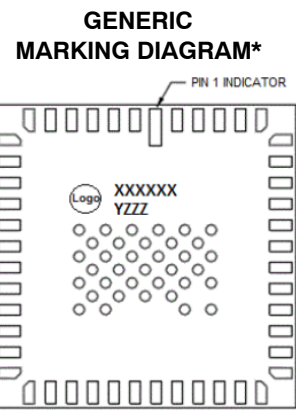
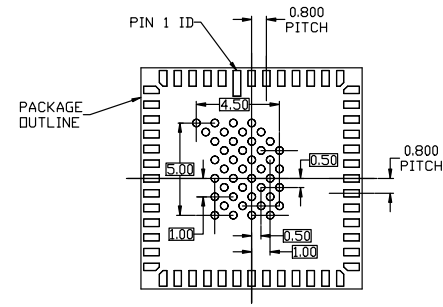
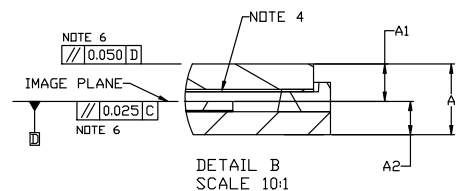
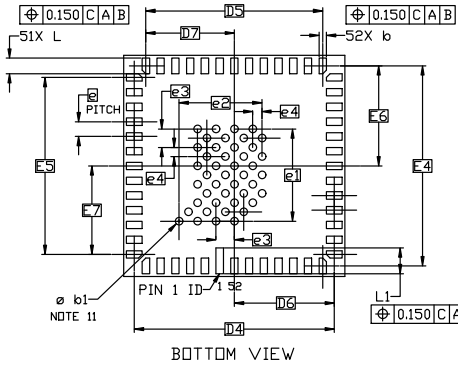
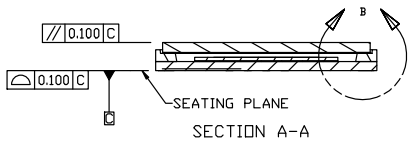
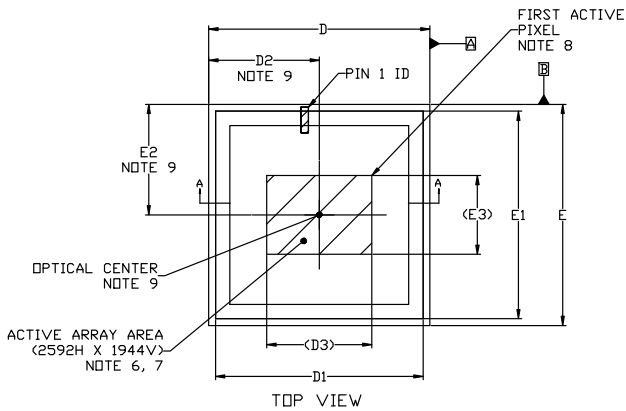
DATE 18 OCT 2023

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. GLASS: 0.550 THICKNESS; REFRACTIVE INDEX = 1.52.
4. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.260 THICKNESS.
5. COPLANARITY APPLIES TO THE PLATED LAND PADS.
6. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
7. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B $\pm 0.5^\circ$.
8. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
9. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.000, 0.000).
10. PACKAGE CENTER (X, Y) = (0.000, 0.000).
11. SOLDER MASK OPENINGS FOR THERMAL CONNECTION PADS.

MILLIMETERS			
DIM	MIN	NDM	MAX
A	1.435	1.535	1.635
A1	0.710	0.810	0.910
A2	0.650	0.725	0.800
b	0.350	0.400	0.450
b1	0.350	0.400	0.450
D	11.900	12.000	12.100
D1	11.210	11.260	11.310
D2	5.900	6.000	6.100
D3	5.702 (REF)		
D4	10.850 BSC		
D5	9.600 BSC		
D6	5.425 BSC		
D7	4.800 BSC		
E	11.900	12.000	12.100

MILLIMETERS			
DIM	MIN	NDM	MAX
E1	11.210	11.260	11.310
E2	5.900	6.000	6.100
E3	4.276 (REF)		
E4	10.850 BSC		
E5	9.600 BSC		
E6	5.425 BSC		
E7	4.800 BSC		
e	0.800 BSC		
e1	5.000 BSC		
e2	4.500 BSC		
e3	1.000 BSC		
e4	0.500 BSC		
L	0.800	0.850	0.900
L1	1.350	1.400	1.450



RECOMMENDED MOUNTING FOOTPRINT*
*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SLDERRM/D.

XXXX = Specific Device Code
Y = Year
ZZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	mPLCC52 12.00x12.00x1.53, 0.80P	PAGE 1 OF 1

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